



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TORNEY DOCKET NO.: AGX-37

In re Application of: Shooshtarian, et al.

Serial No.: 09/527,873

Filed: March 17, 2000

Confirmation No.: 4182

Title: Localized Heating and Cooling of Substrates

Group Art Unit: 2823

Examiner: Hsein-Ming Lee

Our Account No.: 04-1403

Commissioner for Patents
U.S. Patent and Trademark Office
Washington, DC 20231

AMENDMENT AFTER FINAL

This is a response/amendment/letter in the above-identified application and includes the herewith attachment of same date and subject which is incorporated herein by reference and the signature below is to be treated as the signature to the attachment in absence of a signature thereto.

Fee requirements (if any) have been calculated as shown below:

Claims remaining after amendment	Highest number previously paid for	Present Extra	Additional Fee
Total Effective Claims	minus	=	x \$18 =
Independent Claims	minus	=	x \$80 =
If amendment enters <u>proper</u> multiple dependent claim(s) into this application for <u>first</u> time, add \$270.00 (per application)			
Since Official Action set an <u>original</u> due date of			
PETITION is hereby made for an extension to cover the date this response is filed for which the requisite fee is enclosed (1 month \$110; 2 months \$390; 3 months \$890; 4 months \$1390)			
If Terminal Disclaimer enclosed, add Rule 20(d) Official Fee (\$110.00)			
SUBTOTAL:			
If "small entity" verified statement filed [] previously, [] herewith, enter one-half (1/2) of subtotal and <u>subtract</u>			
TOTAL:			
Other: <u>Appendix A</u>			
TOTAL FEE ENCLOSED:			

The Commissioner is hereby authorized to charge any fee specifically authorized hereafter, or any fees in addition to the fee(s) filed, or asserted to be filed, or which should have been filed herewith or concerning any paper filed hereafter, and which may be required under Rules 16-18 (deficiency only) now or hereafter relative to this application and the resulting official document under Rule 20, or credit any overpayment, to our Account No. shown in the heading hereof for which purpose a duplicate copy of this sheet is attached. This statement does not authorize charge of the issue fee in this case.

ADDRESS:
Post Office Box 1449
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DORITY & MANNING**ATTORNEYS AT LAW, P.A.**By Atty: Jason W. Johnston Reg. No.: 45,675Signature: [Signature]

hereby certify that this correspondence and any referenced attachment and fee are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, U.S. Patent and Trademark Office, Washington, DC 20231, on September 17, 2001.

Lynn Watkins

Typed or printed name of person mailing paper or fee)

[Signature]

Signature of person mailing paper or fee)



AF/2823

PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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CAREY
9/21/01

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Commissioner for Patents
Washington, D.C. 20231

AMENDMENT AFTER FINAL

Dear Sir:

In response to the Office Action dated July 18, 2001, please amend the above-captioned application as follows:

IN THE CLAIMS

Please amend claim 1 to read as follows (See also Appendix A):

- not
entire
Le
9/27/01
Sub
E1
1. (Twice Amended) A method for heat treating a semiconductor wafer, said method comprising the steps of:
- placing a semiconductor wafer in a thermal processing chamber that is in communication with a plurality of lamps, said semiconductor wafer defining a plurality of localized regions along a radial axis;
 - adjusting the temperature of said semiconductor wafer to a predetermined temperature according to a predetermined heat cycle, said predetermined heat cycle